Current density and power requirements in servers, switches and storage devices are increasing. TE Connectivity’s (TE) new HD+ card edge connector delivers the highest current density in the market at 15A/2.54mm and supports up to 3000W power supplies for data center equipment.

A unique design with dual layers of DC power contacts and pass-through pin provides multiple mating/contact points to the PCB which helps ensure low contact resistance and supports higher current. The signal pitch is 1.27mm, which is compatible with common industry PCB footprint designs.

APPLICATIONS

- Servers
- Switches
- Storage devices
Extend the life of your power supply unit with the highest current density power connectors in the market.

High Current Density
- 1.27mm signal contact pitch, 5.08mm power contact pitch
- Power contact current: 31A (average)
- Working voltage: 60V DC

Low Contact Resistance
- Unique dual layer design of DC power contacts and pass-through pins provides multiple mating/contact points to the PCB which helps ensure low contact resistance
- DC power contact: 1 mΩ max
- Provides lower temperature rising and lower power loss on the connector

Common PCB Footprint
- Compact and cost-effective design with common power and signal contact module
- Flexible configuration with different contact quantities and positions
- Better scalability (AC & DC, low power & high power)

Reliable Performance
- Excellent mechanical and electrical performance
- Easy mating/un-mating with proper retention force
- Mating force 80N max with nominal mating PCB

Key Features:
- Width: 7.8mm
- PCB thickness: 1.57mm
- Current: 31A avg. (~15.5A/2.54mm)
- Max. resistance: 0.8 milliohm
- Avg. resistance: 0.3 milliohm
- Mating force: 8.5N/contact

Specifications
- Product spec: 108-128060
- Qualification test report: 501-128061

Part Number Information

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<thead>
<tr>
<th>Part Number</th>
<th>Description</th>
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<tbody>
<tr>
<td>2322260-1</td>
<td>HD+ Card Edge Power Connector</td>
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